

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

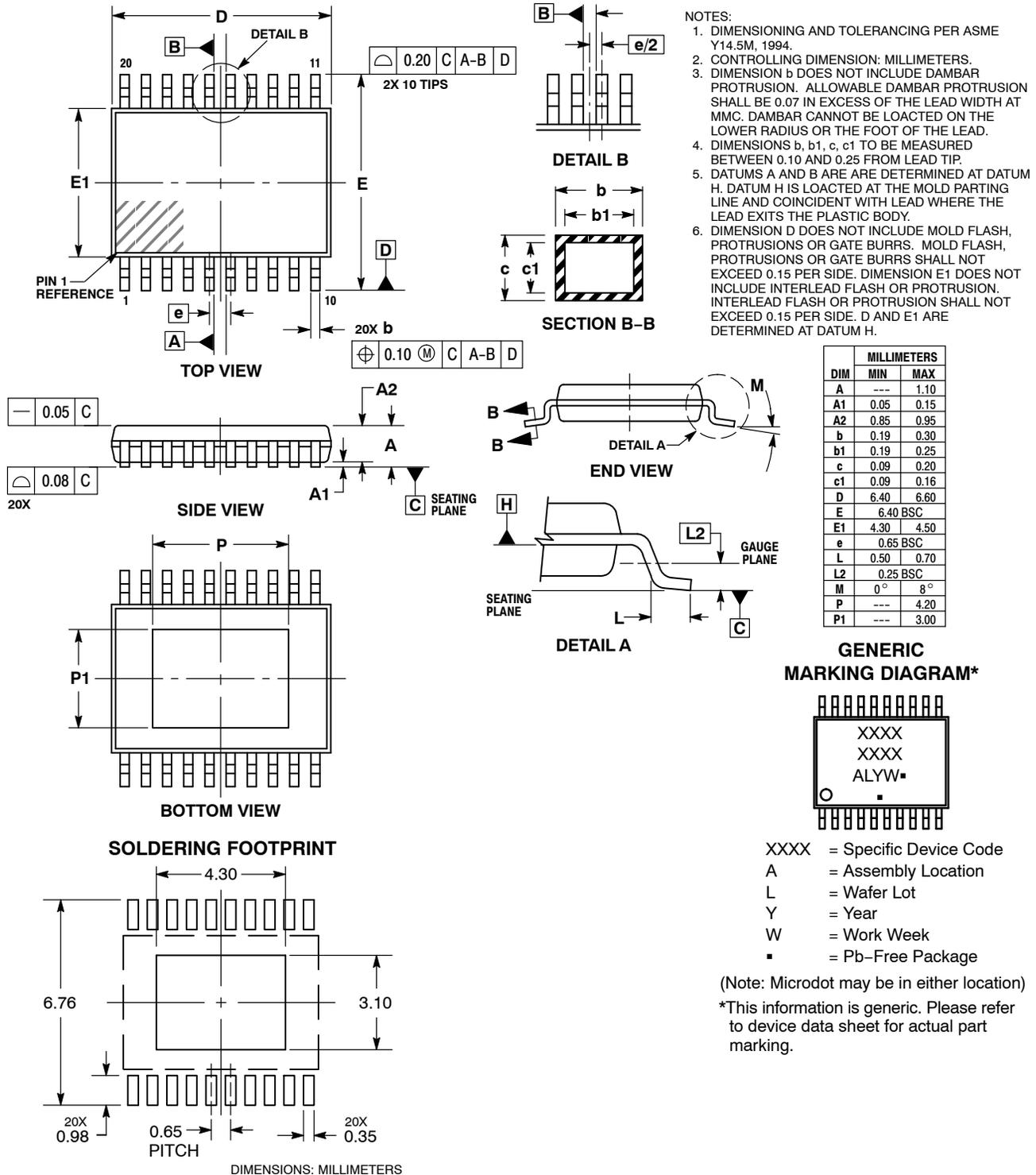
ON Semiconductor®



SCALE 1:1

TSSOP-20 EP
CASE 948AB-01
ISSUE O

DATE 17 JUN 2008



DOCUMENT NUMBER:	98AON30874E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	TSSOP-20 EXPOSED PAD	PAGE 1 OF 2

